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Mobile SDR / DDR / DDR2 PART NUMBERING

H 5 X X XX X X X X X - XX X

1 2 3 4 5 6 7 8 9 10 11 12 13 14

HYNIX MEMORY

PRODUCT FAMILY

5 : DRAM

PRODUCT MODE

5 : Mobile SDR
M : Mobile DDR
L : Mobile DDR2-S4
K : Mobile DDR2-S2

POWER SUPPLY

S : VDD=1.8V & VDDQ=1.8V
D : VDD1=1.8V, VDD2=1.35V, VDDCA & VDDQ=1.2V
R : VDD1=1.8V, VDD2=1.2V, VDDCA & VDDQ=1.2V

DENSITY & REFRESH

64 : 64M / 4K REF / 64ms
12 : 128M / 4K REF / 64ms
26 : 256M / 4K REF / 64ms
25 : 256M / 8K REF / 64ms
51 : 512M / 8K REF / 64ms
1G : 1G / 8K REF / 64ms
2G : 2G / 8K REF / 64ms

ORGANIZATION

8 : x8
6 : x16
2 : x32
3 : x32, Reduced Page Size

NUMBER OF BANKS

1 : 2 Banks
2 : 4 Banks
3 : 8 Banks

OPERATING TEMPERATURE & POWER CONSUMPTION

L : Commercial Temp[1] Low Power
G : Extended Temp[2] & Low Power
M : Mobile Temp[3] & Low Power

SPEED(tCL-tRCD-tRP)

Mobile SDR
A3 : 105MHz 3-3-3
75 : 133MHz 3-3-3
60 : 166MHz 3-3-3

Mobile DDR
L3 : DDR200 3-3-3
K3 : DDR266 3-3-3
J3 : DDR333 3-3-3
Q3 : DDR370 3-3-3
QA : DDR370 4-3-3
E3 : DDR400 3-3-3
EA : DDR400 4-3-3
EB : DDR400 3-4-3

Mobile DDR2
E3 : DDR400 3-3-3
EC : DDR400 3-4-4
C4 : DDR533 4-4-4
CA : DDR533 4-5-5
Y5 : DDR667 5-5-5
YA : DDR667 5-6-6
S6 : DDR800 6-6-6
SA : DDR800 6-8-8

PACKAGE MATERIAL

L : Leaded
P : Lead free (ROHS[4] Compliant)
R : Lead & Halogen free (ROHS[4] Compliant)
A : Wafer only

PACKAGE TYPE

F : FBGA (Wire Bond)
M : FBGA / DDP (Dual Die Package)
W : Wafer
K : KGD
U : ULGA

DIE GENERATION

M : 1st
A : 2nd
B : 3rd
C : 4th
D : 5th
E : 6th
F : 7th
G : 8th

Note:
1) Commercial Temperature : 0℃~70℃
2) Extended Temperature: -25℃~85℃
3) Mobile Temperature: -30℃~85℃
4) ROHS : Restriction Of Hazardous Substances